

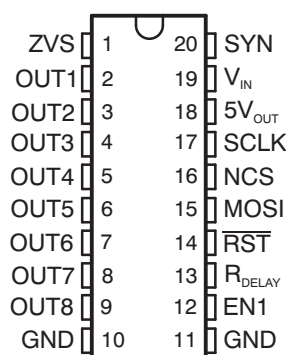
FEATURES

- Eight Low-Side Drivers With Internal Clamp for Inductive Loads and Current Limiting for Self Protection
 - Seven Outputs Rated at 150 mA and Controlled Through Serial Interface
 - One Output Rated at 150 mA and Controlled Through Serial Interface and Dedicated Enable Pin
- 5-V \pm 5% Regulated Power Supply With 200-mA Load Capability at V_{IN} Max of 18 V
- Internal Voltage Supervisory for Regulated Output
- Serial Communications for Control of Eight Low-Side Drivers
- Enable/Disable Input for OUT1
- 5-V or 3.3-V I/O Tolerant for Interface to Microcontroller
- Programmable Power-On Reset Delay Before \overline{RST} Asserted High, Once 5 V Is Within Specified Range (6 ms Typ)
- Programmable Deglitch Timer Before \overline{RST} Asserted Low (40 μ s Typ)
- Zero-Voltage Detection Signal
- Thermal Shutdown for Self Protection

APPLICATIONS

- Electrical Appliances
 - Air Conditioning Units
 - Ranges
 - Dishwashers
 - Refrigerators
 - Microwaves
 - Washing Machines
- General-Purpose Interface Circuits, Allowing Microcontroller Interface to Relays, Electric Motors, LEDs, and Buzzers

N OR PWP PACKAGE
(TOP VIEW)



DESCRIPTION/ORDERING INFORMATION

The power supply provides regulated 5-V output to power the system microcontroller and drive eight low-side switches. The ac zero-detect circuitry is monitoring the crossover voltage of the mains ac supply. The resultant signal is a low-frequency clock output on the ZVS terminal, based on the ac-line cycle. This information allows the microcontroller to reduce in-rush current by powering loads on the ac-line peak voltage.

A serial communications interface controls the eight low-side outputs; each output has an internal snubber circuit to absorb the energy in the inductor at turn OFF. Alternatively, the system can use a fly-back diode to V_{IN} to help recirculate the energy in an inductive load at turn OFF.

ORDERING INFORMATION⁽¹⁾

T_A	PACKAGE ⁽²⁾		ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 125°C	PDIP – N	Tube of 20	TPL9201N	TPL9201N
	PowerPAD™ – PWP	Reel of 2000	TPL9201PWPR	PL201
		Tube of 70	TPL9201PWP	

- (1) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at www.ti.com.
- (2) Package drawings, thermal data, and symbolization are available at www.ti.com/packaging.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PowerPAD is a trademark of Texas Instruments.

TPL9201

8-CHANNEL RELAY DRIVER

WITH INTEGRATED 5-V LDO AND ZERO-VOLT DETECTION

SLIS123D–JUNE 2006–REVISED FEBRUARY 2008

PINOUT CONFIGURATION

NO.	NAME	I/O	DESCRIPTION
1	ZVS	O	Zero-voltage synchronization
2	OUT1	O	Low-side output 1
3	OUT2	O	Low-side output 2
4	OUT3	O	Low-side output 3
5	OUT4	O	Low-side output 4
6	OUT5	O	Low-side output 5
7	OUT6	O	Low-side output 6
8	OUT7	O	Low-side output 7
9	OUT8	O	Low-side output 8
10 ⁽¹⁾	GND	I	Ground
11 ⁽¹⁾	GND	I	Ground
12	EN1	I	Enable/disable for OUT1
13	R _{DELAY}	O	Power-up reset delay
14 ⁽²⁾	$\overline{\text{RST}}$	I/O	Power-on reset output (open drain, active low)
15	MOSI	I	Serial data input
16	NCS	I	Chip select
17	SCLK	I	Serial clock for data synchronization
18	5V _{OUT}	O	Regulated output
19	V _{IN}	I	Unregulated input voltage source
20	SYN	I	AC zero detect input

(1) Terminals 10 and 11 are fused internally in the lead frame for the 20-pin PDIP package.

(2) Terminal 14 can be used as an input or an output.

TPL9201

8-CHANNEL RELAY DRIVER

WITH INTEGRATED 5-V LDO AND ZERO-VOLT DETECTION

SLIS123D–JUNE 2006–REVISED FEBRUARY 2008

DETAILED DESCRIPTION

The 5-V regulator is powered from V_{IN} , and the regulated output is within $5\text{ V} \pm 5\%$ over the operating conditions. The open-drain power-on reset ($\overline{\text{RST}}$) pin remains low until the regulator exceeds the set threshold, and the timer value set by the capacitor on the reset delay (R_{DELAY}) pin expires. If both of these conditions are satisfied, $\overline{\text{RST}}$ is asserted high. This signifies to the microcontroller that serial communications can be initiated to the TPL9201.

The serial communications is an 8-bit format, with data transfer synchronized using a serial clock from the microcontroller. A single register controls all the outputs (one bit per output). The default value is zero (OFF). If an output requires pulse width modulation (PWM) function, the register must be updated at a rate faster than the desired PWM frequency. OUT1 can be controlled by serial input from the microcontroller or with the dedicated enable (EN1) pin. If EN1 is pulled low or left open, the serial input through the shift register controls OUT1. If EN1 is pulled high, OUT1 always is turned on, and the serial input for OUT1 is ignored.

The SYN input translates the image of the mains voltage through the secondary of the transformer. The SYN input has a resistor to protect from high currents into the IC. The zero-voltage synchronization output translates the ac-line cycle frequency into a low-frequency clock, which can be used for a timing reference and to help power loads on the ac-line peak voltage (to reduce in-rush currents).

If $\overline{\text{RST}}$ is asserted, all outputs are turned OFF internally, and the input register is reset to all zeroes. The microcontroller must write to the register to turn the outputs ON again.

Absolute Maximum Ratings⁽¹⁾

			MIN	MAX	UNIT
$V_{I(unreg)}$ Unregulated input voltage ^{(2) (3)}	V_{IN}			24	V
	SYN			24	
$V_{I(logic)}$ Logic input voltage ^{(2) (3)}	EN1, MOSI, SCLK, and NCS			7	V
	\overline{RST} and R_{DELAY}			7	
V_O Low-side output voltage	OUT1–OUT8			16.5	V
I_{LIMIT} Output current limit ⁽⁴⁾	OUTn = ON and shorted to V_{IN} with low impedance			350	mA
θ_{JA} Thermal impedance, junction to ambient ⁽⁵⁾	N package			69	°C/W
	PWP package			33	
θ_{JC} Thermal impedance, junction to case ⁽⁵⁾	N package			54	°C/W
	PWP package			20	
θ_{JP} Thermal impedance, junction to thermal pad ⁽⁵⁾	PWP package			1.4	°C/W
P_D Continuous power dissipation ⁽⁶⁾	N package			1.8	W
	PWP package			3.7	
ESD Electrostatic discharge ⁽⁷⁾				2	kV
T_A Operating ambient temperature range			–40	125	°C
T_{stg} Storage temperature range			–65	125	°C
T_{lead} Lead temperature	Soldering, 10 s			260	°C

- (1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) All voltage values are with respect to GND.
- (3) Absolute negative voltage on these pins must not go below –0.5 V.
- (4) Not more than one output should be shorted at a time, and duration of the short circuit should not exceed 1 ms.
- (5) The thermal data is based on using 1-oz copper trace with JEDEC 51-5 test board for PWP and JEDEC 51-7 test board for N.
- (6) The data is based on ambient temperature of 25°C max.
- (7) The Human-Body Model is a 100-pF capacitor discharged through a 1.5-k Ω resistor into each pin.

Dissipation Ratings

PACKAGE	$T_A \leq 25^\circ\text{C}$ POWER RATING	DERATING FACTOR ABOVE $T_A = 25^\circ\text{C}$	$T_A = 125^\circ\text{C}$ POWER RATING
N	1812 mW	14.5 mW/°C	362 mW
PWP	3787 mW	30.3 mW/°C	757 mW

Recommended Operating Conditions

			MIN	MAX	UNIT
$V_{I(unreg)}$ Unregulated input voltage	V_{IN}		7	18	V
	SYN		0	18	
$V_{I(logic)}$ Logic input voltage	EN1, MOSI, SCLK, NCS, \overline{RST} , and R_{DELAY}		0	5.25	V
T_A Operating ambient temperature			–40	125	°C

TPL9201

8-CHANNEL RELAY DRIVER

WITH INTEGRATED 5-V LDO AND ZERO-VOLT DETECTION

SLIS123D–JUNE 2006–REVISED FEBRUARY 2008

Electrical Characteristics

$T_A = -40^{\circ}\text{C}$ to 125°C , $V_{IN} = 7\text{ V}$ to 18 V (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN		TYP ⁽¹⁾		MAX		UNIT
Supply Voltage and Current										
V _{IN} ⁽²⁾	Input voltage			7				18		V
I _{VIN}	Input supply current	Enable = ON, OUT1–OUT8 = Off						3		mA
		Enable = ON, OUT1–OUT8 = On						5		
Logic Inputs (MOSI, NCS, SCLK, and EN1)										
V _{IL}	Logic input low level	I _{IL} = 100 μA						0.8		V
V _{IH}	Logic input high level	I _{IL} = 100 μA		2.4						
Reset (RST)										
V _{OL}	Low-level logic output	I _{OL} = 1.6 mA						0.4		V
V _{OH} ⁽³⁾	High-level logic output	5-kΩ pullup to V _{CC}		V _{CC} – 0.8						V
V _H	Disabling reset threshold	5-V regulator ramps up				4.25		4.5		V
V _L	Enabling reset threshold	5-V regulator ramps down		3.3		3.75				V
V _{HYS}	Threshold hysteresis			0.12		0.5				V
Reset Delay (R _{DELAY})										
I _{OUT}	Output current			18		28		48		μA
T _{DW}	Reset delay timer	C = 47 nF		3		6				ms
T _{UP}	Reset capacitor to low level	C = 47 nF				45				μs
Output (OUT1–OUT8)										
V _{OL}	Output ON	I _{OUTn} = 150 mA				0.4		0.7		V
I _{OH}	Output leakage	V _{OH} = Max of 16.5 V						2		μA
Regulator Output (5V _{OUT})										
5V _{OUT}	Output supply	I _{5VOUT} = 5 mA to 200 mA, V _{IN} = 7 V to 18 V, C _{5VOUT} = 1 μF		4.75		5		5.25		V
I _{5VOUT} limit	Output short-circuit current	5V _{OUT} = 0 V		200						mA
Thermal Shutdown										
T _{SD}	Thermal shutdown					150				°C
T _{HYS}	Hysteresis					20				°C
Zero Voltage Synchronization (ZVS)										
V _{SYNTH}	Transition threshold			0.4		0.75		1.1		V
I _{SYN}	Input activating current	R _{ZV} = 10 kΩ, V _{SYN} = 24 V						2		mA
t _D	Transition time	Rising and falling		10						μs

(1) All typical values are at $T_A = 25^{\circ}\text{C}$.

(2) There are external high-frequency noise-suppression capacitors and filter capacitors on V_{IN} .

(3) V_{CC} is the pullup resistor voltage.

Output Control Register

MSB				LSB			
IN8	IN7	IN6	IN5	IN4	IN3	IN2	IN1
0	0	0	0	0	0	0	0

INn = 0: Output OFF

INn = 1: Output ON

To operate the output in PWM mode, the output control register must be updated at a rate twice the desired PWM frequency of the output. Maximum PWM frequency is 5 kHz. The register is updated every 100 μ s.

ENABLE TRUTH TABLE

EN1	SERIAL INPUT FOR OUT1	OUT1
Open	H	On
Open	L	Off
L	H	On
L	L	Off
H	H	On
H	L	On

TPL9201

8-CHANNEL RELAY DRIVER

WITH INTEGRATED 5-V LDO AND ZERO-VOLT DETECTION

SLIS123D–JUNE 2006–REVISED FEBRUARY 2008

Serial Communications Interface

The serial communications is an 8-bit format, with data transfer synchronized using a serial clock from the microcontroller (see [Figure 1](#)). A single register controls all the outputs. The signal gives the instruction to control the output of TPL9201.

The NCS signal enables the SCLK and MOSI data when it is low. After NCS is set low for T_1 , synchronization clock and data begin to transmit and, after the 8-bit data has been transmitted, NCS is set high again to disable SCLK and MOSI and transfer the serial data to the control register. SCLK must be held low when NCS is in the high state.

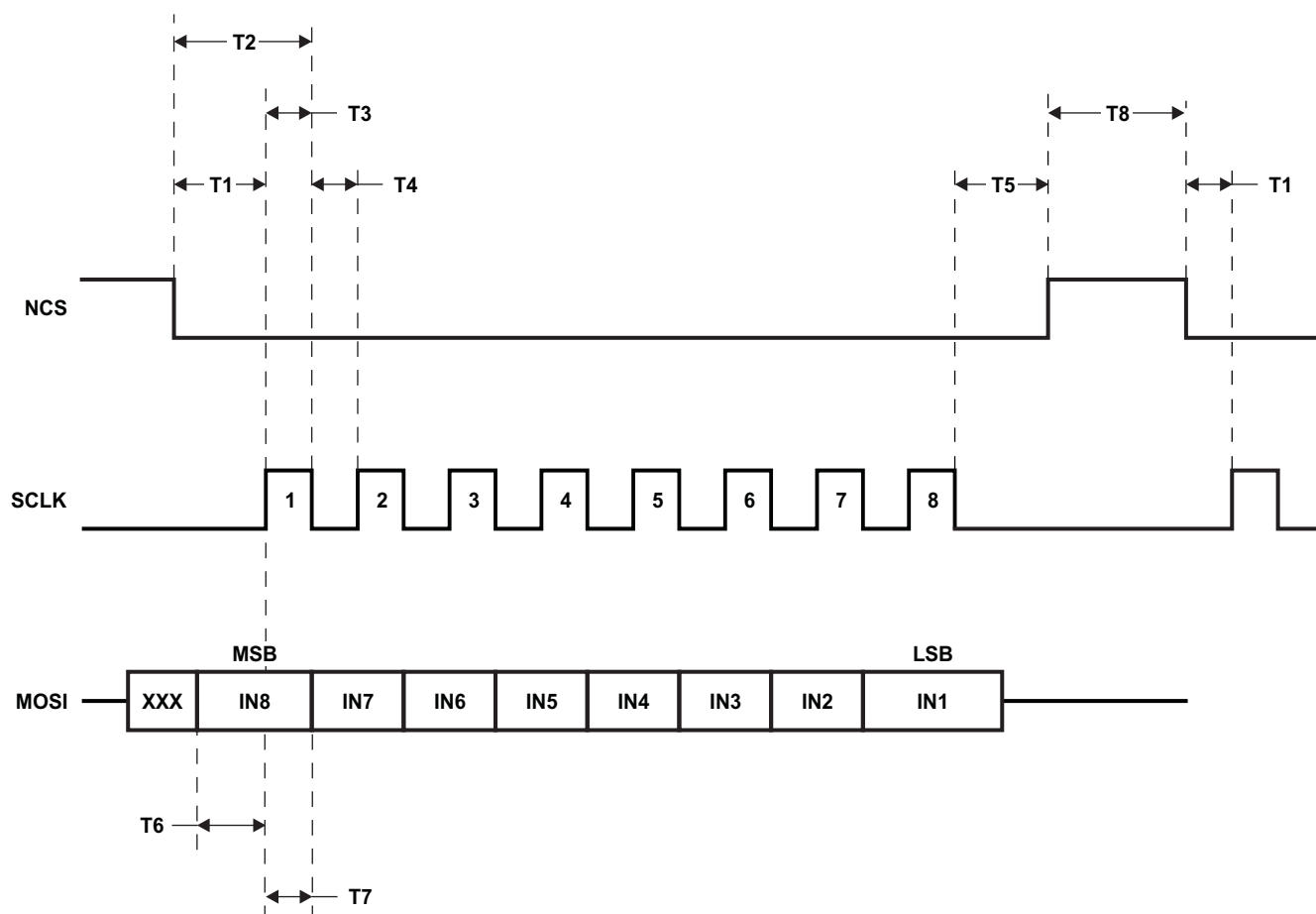


Figure 1. Serial Communications

Timing Requirements

$T_A = -40^{\circ}\text{C}$ to 125°C , $V_{IN} = 7\text{ V}$ to 18 V (unless otherwise noted)

		MIN	TYP	MAX	UNIT
f_{SPI}	SPI frequency		4		MHz
T1	Delay time, NCS falling edge to SCLK rising edge	10			ns
T2	Delay time, NCS falling edge to SCLK falling edge	80			ns
T3	Pulse duration, SCLK high	60			ns
T4	Pulse duration, SCLK low	60			ns
T5	Delay time, last SCLK falling edge to NCS rising edge	80			ns
T6	Setup time, MOSI valid before SCLK edge	10			ns
T7	Hold time, MOSI valid after SCLK edge	10			ns
T8	Time between two words for transmitting	170			ns

Reset Delay (R_{DELAY})

The R_{DELAY} output provides a constant current source to charge an external capacitor to approximately 6.5 V. The external capacitor is selected to provide a delay time, based on the current equation for a capacitor, $I = C(\Delta v/\Delta t)$ and a 28- μA typical output current.

Therefore, the user should select a 47-nF capacitor to provide a 6-ms delay at 3.55 V.

$$I = C(\Delta v/\Delta t)$$

$$28\text{ }\mu\text{A} = C \times (3.55\text{ V}/6\text{ ms})$$

$$C = 47\text{ nF}$$

TPL9201

8-CHANNEL RELAY DRIVER

WITH INTEGRATED 5-V LDO AND ZERO-VOLT DETECTION

SLIS123D–JUNE 2006–REVISED FEBRUARY 2008

APPLICATION INFORMATION

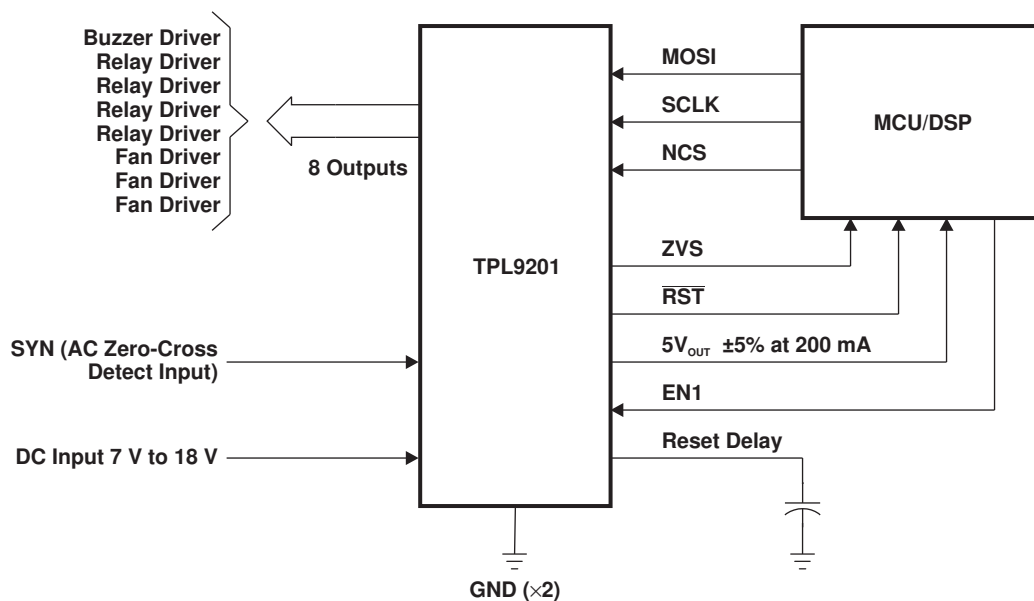


Figure 2. Typical Application

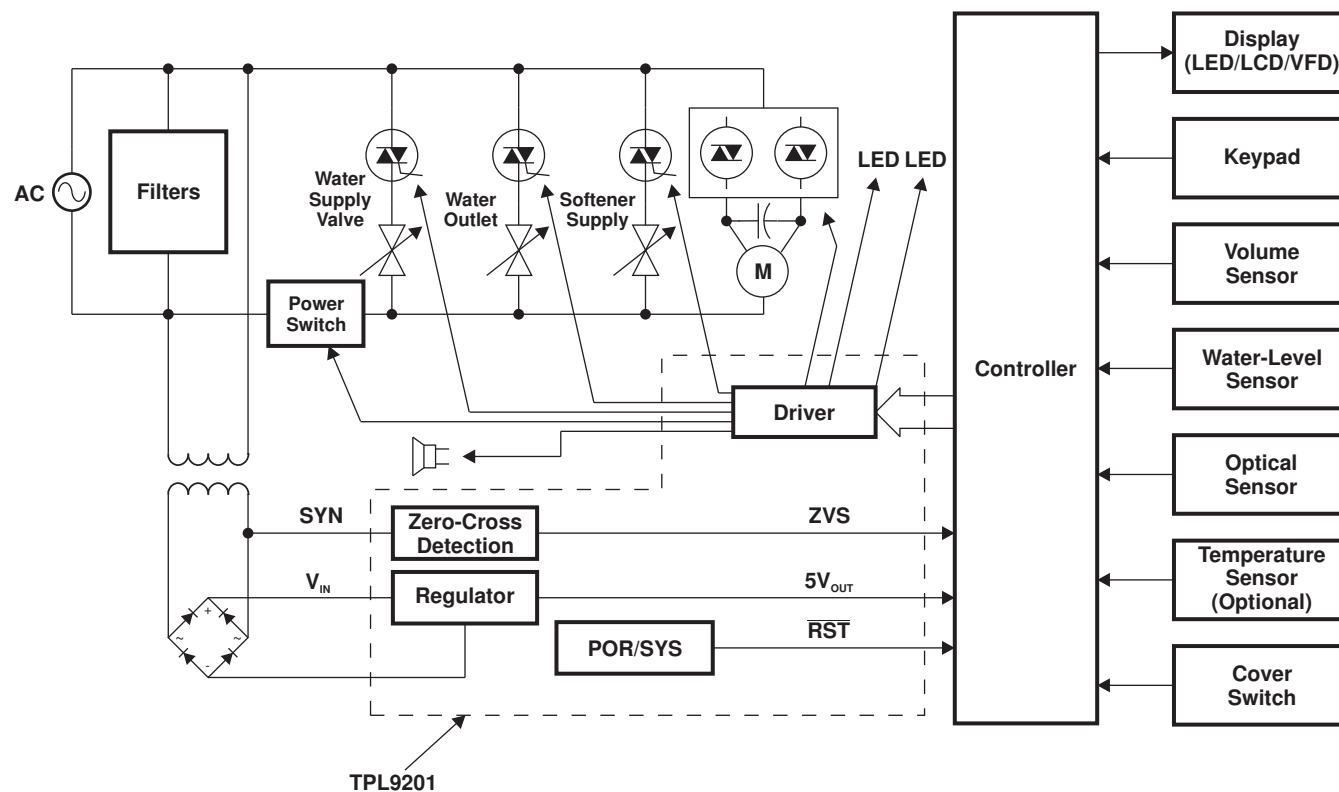


Figure 3. Washing-Machine Application

PCB Layout

To maximize the efficiency of this package for application on a single-layer or multilayer PCB, certain guidelines must be followed when laying out this part on the PCB.

The following information is to be used as a guideline only.

For further information, see the PowerPAD concept implementation document.

Application Using a Multilayer PCB

In a multilayer board application, the thermal vias are the primary method of heat transfer from the package thermal pad to the internal ground plane (see Figure 4 and Figure 5).

The efficiency of this method depends on several factors: die area, number of thermal vias, thickness of copper, etc. (see the *PowerPAD™ Thermally Enhanced Package Technical Brief*, literature number [SLMA002](#)).

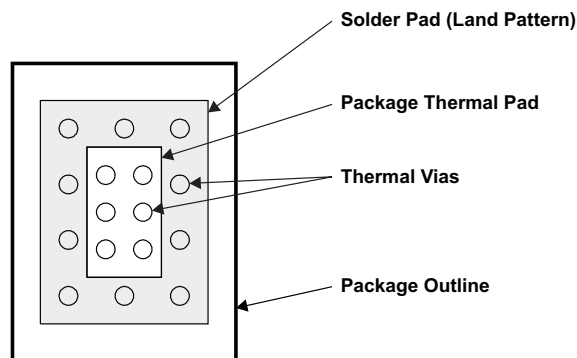


Figure 4. Package and PCB Land Configuration for a Multilayer PCB

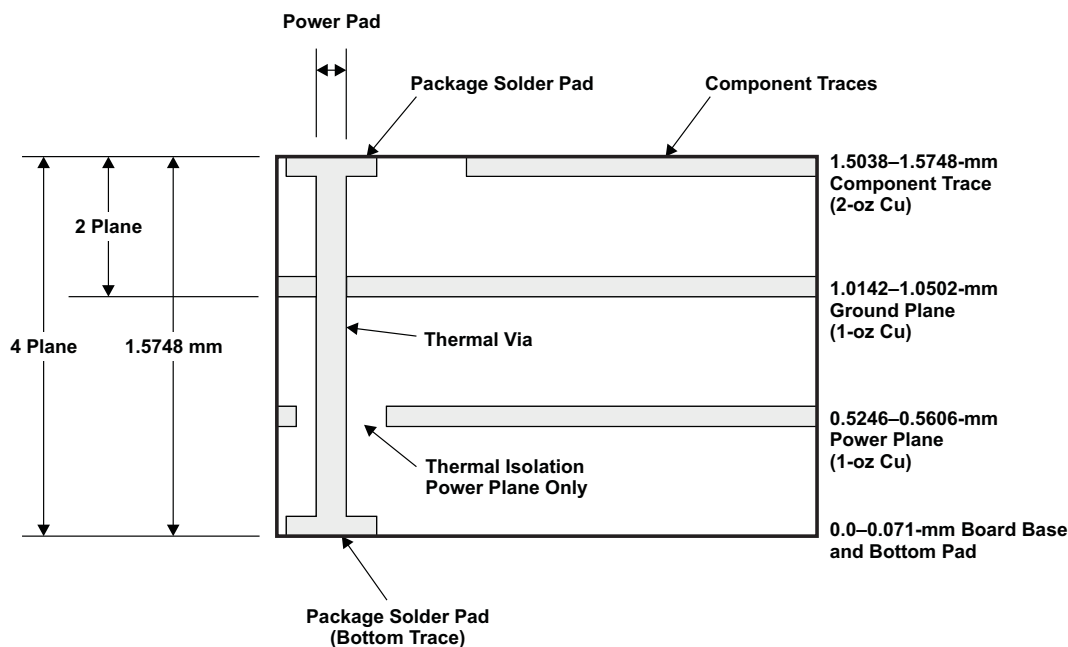


Figure 5. Multilayer Board (Side View)

Application Using a Single-Layer PCB

In a single-layer board application, the thermal pad is attached to a heat spreader (copper area) by using the low thermal-impedance attachment method (solder paste or thermal-conductive epoxy). With either method, it is advisable to use as much copper trace area as possible to dissipate the heat.

TPL9201

8-CHANNEL RELAY DRIVER

WITH INTEGRATED 5-V LDO AND ZERO-VOLT DETECTION

SLIS123D—JUNE 2006—REVISED FEBRUARY 2008

CAUTION:

If the attachment method is not implemented correctly, the functionality of the product cannot be ensured. Power-dissipation capability is adversely affected if the device is incorrectly mounted onto the circuit board.

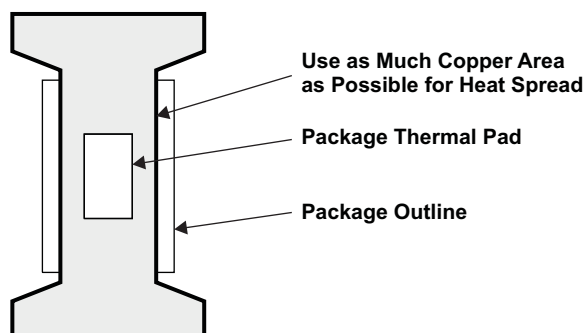


Figure 6. Layout Recommendations for a Single-Layer PCB

Recommended Board Layout

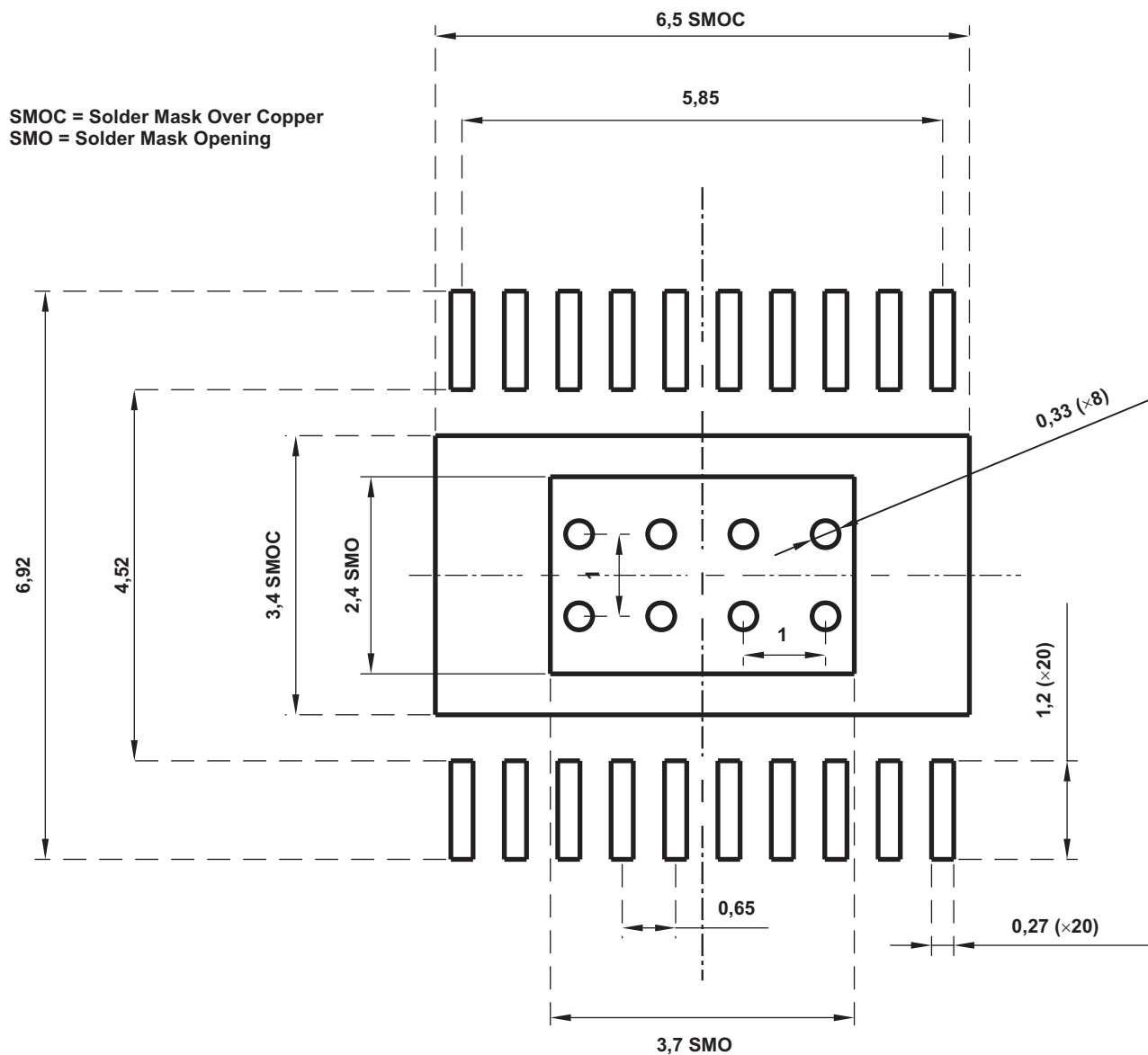


Figure 7. Recommended Board Layout for PWP

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
TPL9201PWP	Active	Production	HTSSOP (PWP) 20	70 TUBE	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	PL201
TPL9201PWP.A	Active	Production	HTSSOP (PWP) 20	70 TUBE	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	PL201
TPL9201PWPR	Active	Production	HTSSOP (PWP) 20	2000 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	PL201
TPL9201PWPR.A	Active	Production	HTSSOP (PWP) 20	2000 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	PL201

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

TAPE AND REEL INFORMATION



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TPL9201PWPR	HTSSOP	PWP	20	2000	330.0	16.4	6.95	7.1	1.6	8.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TPL9201PWPR	HTSSOP	PWP	20	2000	350.0	350.0	43.0

TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
TPL9201PWP	PWP	HTSSOP	20	70	530	10.2	3600	3.5
TPL9201PWP.A	PWP	HTSSOP	20	70	530	10.2	3600	3.5

GENERIC PACKAGE VIEW

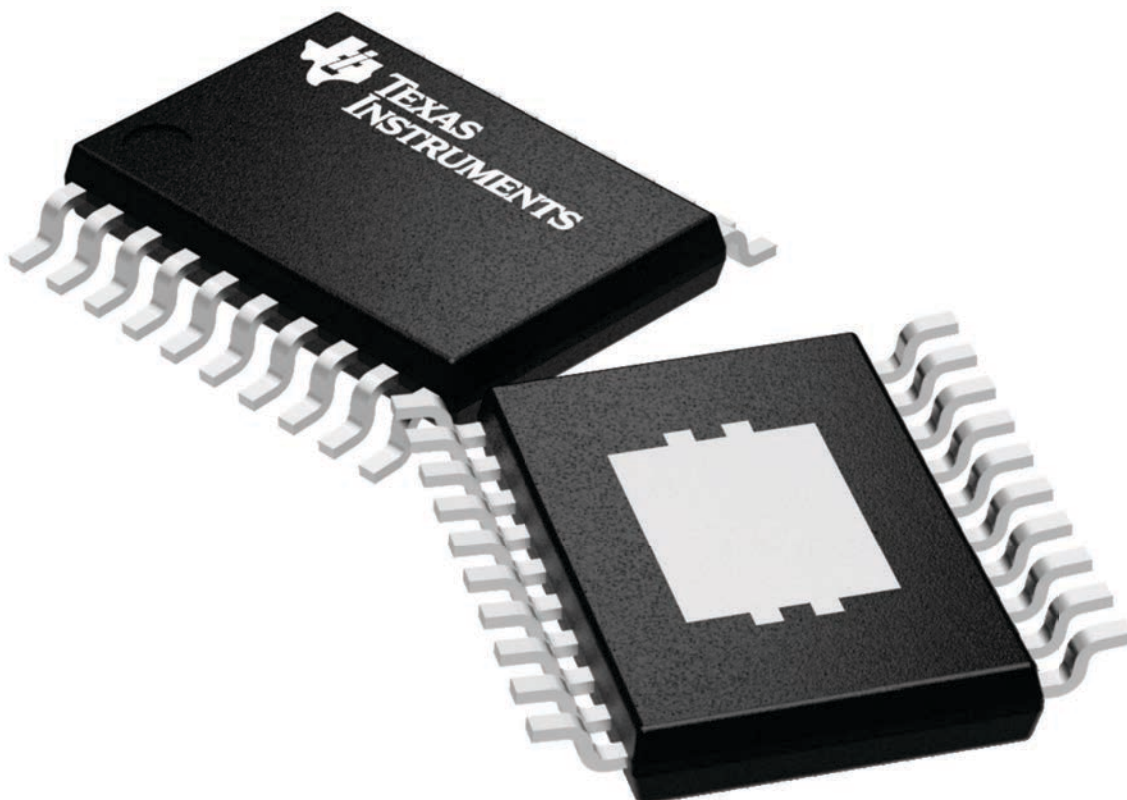
PWP 20

HTSSOP - 1.2 mm max height

6.5 x 4.4, 0.65 mm pitch

SMALL OUTLINE PACKAGE

This image is a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.



4224669/A



PowerPAD™ TSSOP - 1.2 mm max height

Technical drawing of a 24-pin connector. The drawing includes three views: a top view, a side view, and a detail view (DETAIL A).

Top View Dimensions:

- Overall width: 6.6 TYP, 6.2
- Pin 1 Index Area: 6.6, 6.4, NOTE 3
- Pin pitch: 18X 0.65
- Pin 10 to Pin 20 distance: 2X 5.85
- Pin 10 to Pin 11 distance: 20X 0.30, 0.17
- Pin 10 to Pin 11 distance: 4.5, 4.3
- Pin 10 to Pin 11 distance: 2X 0.7 MAX, NOTE 5
- Pin 10 to Pin 11 distance: 2X 0.27 MAX, NOTE 5
- Pin 10 to Pin 11 distance: 3.64, 2.94
- Pin 10 to Pin 11 distance: 2.79, 2.24

Side View Dimensions:

- Seating Plane: 0.1
- Pin 10 to Pin 20 distance: 4X (0°-12°)

Detail A (Typical):

- Pin 10 to Pin 11 distance: 0.25
- Pin 10 to Pin 11 distance: 0.75, 0.50
- Pin 10 to Pin 11 distance: 1.2 MAX
- Pin 10 to Pin 11 distance: 0.15, 0.05
- Pin 10 to Pin 11 distance: 0°-8°

Callouts:

- PIN 1 INDEX AREA
- SEE DETAIL A
- THERMAL PAD
- SEATING PLANE
- DETAIL A TYPICAL

PowerPAD is a trademark of Texas Instruments.

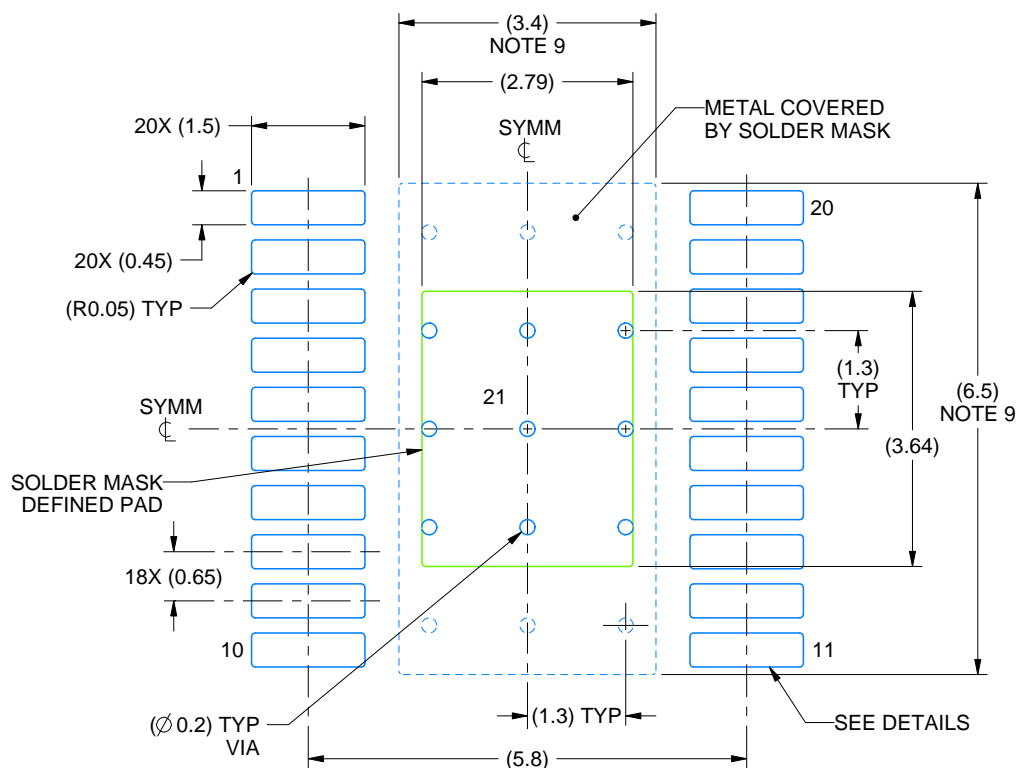
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. Reference JEDEC registration MO-153.
5. Features may differ or may not be present.

EXAMPLE BOARD LAYOUT

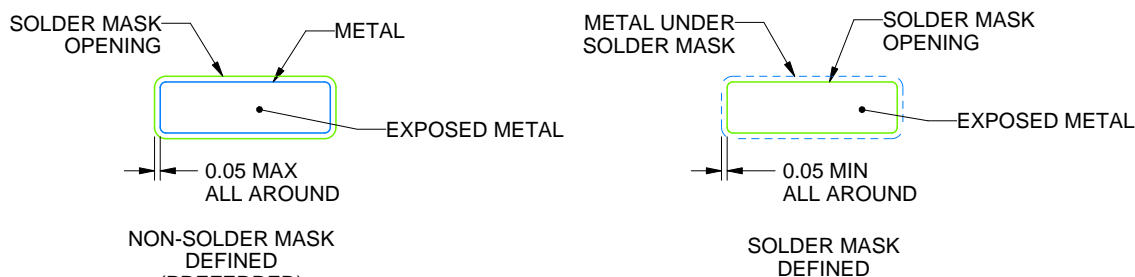
PWP0020W

PowerPAD™ TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X



SOLDER MASK DETAILS

4231145/A 08/2024

NOTES: (continued)

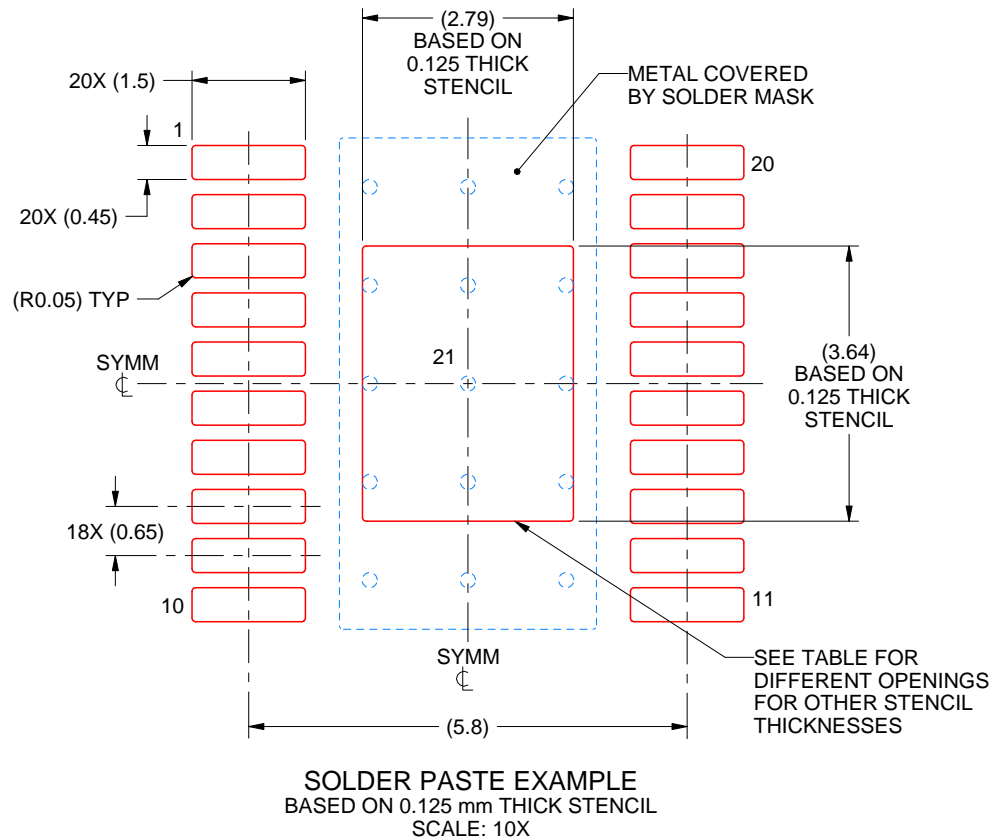
6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.
8. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature numbers SLMA002 (www.ti.com/lit/slma002) and SLMA004 (www.ti.com/lit/slma004).
9. Size of metal pad may vary due to creepage requirement.
10. Vias are optional depending on application, refer to device data sheet. It is recommended that vias under paste be filled, plugged or tented.

EXAMPLE STENCIL DESIGN

PWP0020W

PowerPAD™ TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



STENCIL THICKNESS	SOLDER STENCIL OPENING
0.1	3.12 X 4.07
0.125	2.79 X 3.64 (SHOWN)
0.15	2.55 X 3.32
0.175	2.36 X 3.08

4231145/A 08/2024

NOTES: (continued)

11. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
12. Board assembly site may have different recommendations for stencil design.

IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATA SHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, regulatory or other requirements.

These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to [TI's Terms of Sale](#) or other applicable terms available either on [ti.com](https://www.ti.com) or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products.

TI objects to and rejects any additional or different terms you may have proposed.

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
Copyright © 2025, Texas Instruments Incorporated